

LISTING OF CLAIMS

The present listing consists of all claims in the application and supersedes any prior listing of claims.

1-37. (Cancelled).

38. (New). An apparatus comprising:
 a dielectric substrate;
 a metallic surface on said dielectric substrate;
 a layer of a first polymer provided on said metallic surface, said first polymer being a water-soluble, cationic material having a weight average molecular weight of about 100,000; and
 a layer of a second polymer provided on said first polymer, said second polymer being a non-water-soluble material.

39. (New). The apparatus of Claim 38, wherein said metallic surface is selected from the group consisting of copper, gold, aluminum, silver, titanium, tantalum, tungsten, niobium, alloys thereof, silicides thereof, and intermetallic compounds thereof.

40. (New). The apparatus of Claim 38, wherein said metallic surface is copper.

41. (New). The apparatus of Claim 38, wherein said metallic surface is gold.

42. (New). The apparatus of Claim 38, wherein said second polymer is selected from the group consisting of polymers of acrylates and methacrylates.

43. (New). The apparatus of Claim 38, wherein said first polymer is selected from the group consisting of polymers of acrylamides and amidoamines.

44. (New). The apparatus of Claim 38, wherein said first polymer has a weight average molecular weight of from about 500,000 to about 1,000,000.

45. (New). The apparatus of Claim 38, wherein said layer of a first polymer is a monolayer.
46. (New). The apparatus of Claim 38, wherein said layer of a first polymer is less than a monolayer.
47. (New). The apparatus of Claim 38, wherein said layer of a first polymer covers at least 25% of said metallic surface.